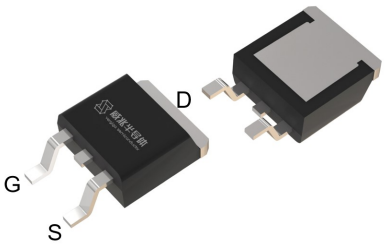
V_{DS}	100	V
$R_{DS(on),TYP}$@ V_{GS}=10 V	1.8	mΩ
$I_{D(Wire\ bond\ Limited)}$	195	A

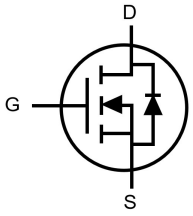
Features

- Enhancement mode
- Low RDS(on) to minimize conduction losses
- VitoMOS® Ⅱ Technology
- 100% Avalanche Tested
- Optimized Qg, Qgd, and Qgd/Qgs ratio to minimize switching losses

TO-263



Pb-Free RoHS HF Halogen-Free



Part ID	Package Type	Marking	Packing
VS1891GMH	TO-263	1891GMH	800pcs/Reel

Maximum ratings, at T_A =25°C, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		100	V
V_{GS}	Gate-Source voltage		±20	V
I_S	Diode continuous forward current (Wire bond limited)	T_C = 25°C	195	A
I_D	Continuous drain current @VGS=10V (Wire bond limited)	T_C = 25°C	195	A
I_D	Continuous drain current @VGS=10V (Wire bond limited)	T_C = 100°C	195	A
I_{DM}	Pulse drain current tested ①	T_C = 25°C	955	A
I_{DSM}	Continuous drain current @VGS=10V	T_A = 25°C	20	A
		T_A = 70°C	16	A
EAS	Maximum Avalanche energy, single pulsed ②		2116	mJ
P_D	Maximum power dissipation ③	T_C = 25°C	536	W
P_{DSM}	Maximum power dissipation ④	T_A = 25°C	2.1	W
T_J,T_{STG}	Operating Junction and Storage Temperature Range		-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typical	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case ⑤	0.23	0.28	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient ⑥	50	60	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max	Unit
Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=1mA	100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current(Tj=25℃)	V_{DS}=100V,V_{GS}=0V	--	--	1	μA
	Zero Gate Voltage Drain Current(Tj=125℃)⑦	V_{DS}=100V,V_{GS}=0V	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS}=±20V,V_{DS}=0V	--	--	±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS},I_D=250μA	2.5	3	3.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance ⑧	V_{GS}=10V, I_D=80A	--	1.8	2.4	mΩ
		Tj=100℃ ⑦	--	2.7	--	mΩ
Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)						
Ciss	Input Capacitance ⑦	V_{DS}=50V,V_{GS}=0V, f=100KHz	--	12560	--	pF
Coss	Output Capacitance ⑦		--	1810	--	pF
Crss	Reverse Transfer Capacitance ⑦		--	30	--	pF
Rg	Gate Resistance ⑦	f=1MHz	--	2.1	--	Ω
Qg	Total Gate Charge ⑦	V_{DS}=50V,I_D=80A, V_{GS}=10V	--	200	--	nC
Qgs	Gate-Source Charge ⑦		--	58	--	nC
Qgd	Gate-Drain Charge ⑦		--	48	--	nC
Switching Characteristics ⑦						
Td(on)	Turn-on Delay Time	V_{DD}=50V, I_D=80A, R_G=3Ω, V_{GS}=10V	--	34	--	ns
Tr	Turn-on Rise Time		--	119	--	ns
Td(off)	Turn-Off Delay Time		--	113	--	ns
Tf	Turn-Off Fall Time		--	92	--	ns
Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)						
V_{SD}	Forward on voltage	I_{SD}=80A,V_{GS}=0V	--	0.86	1	V
Trr	Reverse Recovery Time ⑦	V_{DD}=80V I_{sd}=80A, V_{GS}=0V di/dt=100A/μs	--	98	--	ns
Qrr	Reverse Recovery Charge ⑦		--	144	--	nC

NOTE:

① Single pulse; pulse width ≤ 100μs.

② This maximum value is based on starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 92A, V_{GS} =10V； 100% FT tested at L = 0.5mH, I_{AS} = 51A.

③ The power dissipation Pd is based on Tj(max), using junction-to-case thermal resistance RθJC.

④ The power dissipation Pdsm is based on Tj(max), using junction-to-ambient thermal resistance RθJA.

⑤ Thermal resistance from junction to soldering point (on the exposed drain pad).

⑥ The value of RθJA is measured with the device in a still air environment with TA =25° C.

⑦ Guaranteed by design, not subject to production testing.

⑧ Pulse width ≤ 380μs; duty cycle≤ 2%.

Typical Characteristics

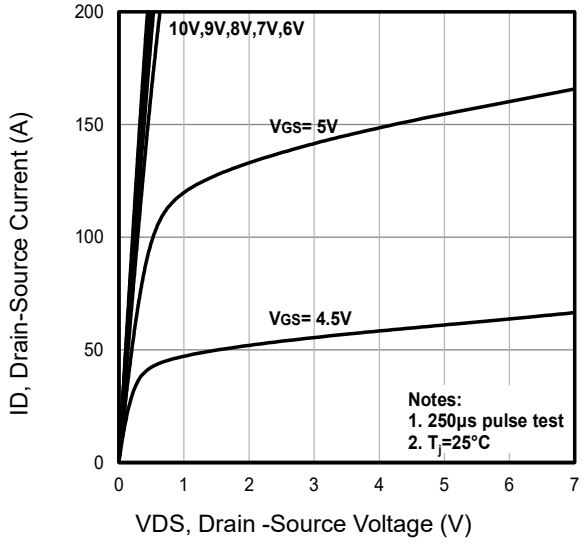


Fig1. Typical Output Characteristics

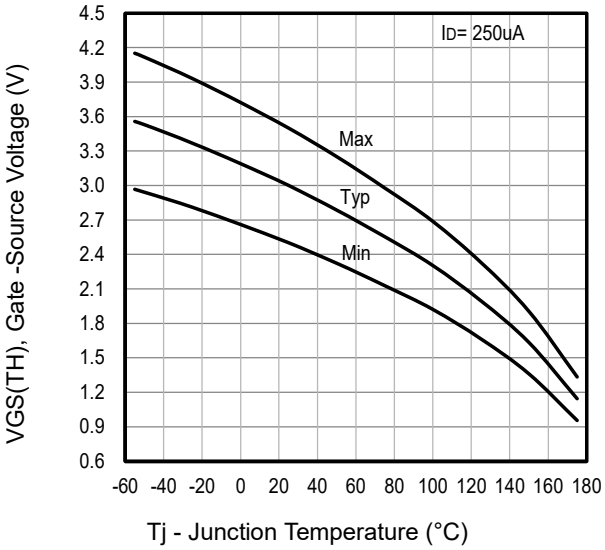


Fig2. Typical $V_{GS(TH)}$ Gate -Source Voltage Vs. Tj

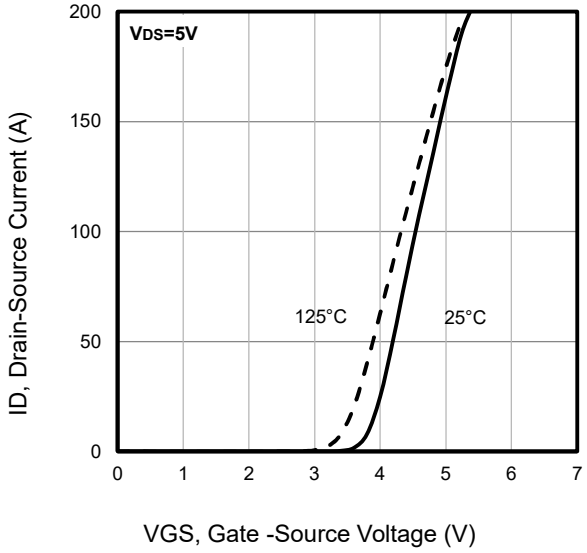


Fig3. Typical Transfer Characteristics

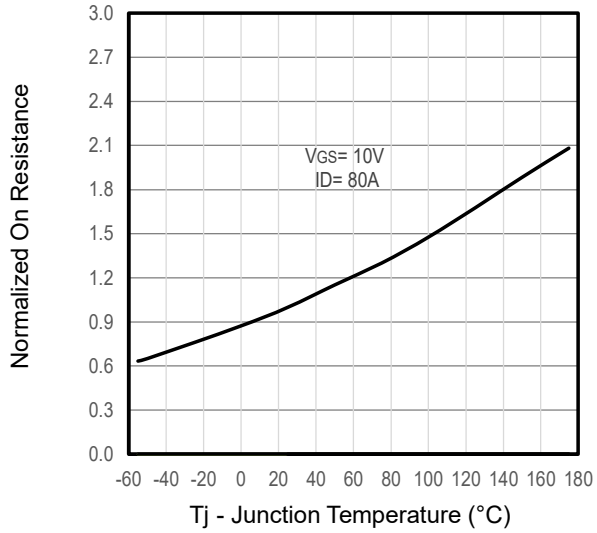


Fig4. Typical Normalized On-Resistance Vs. Tj

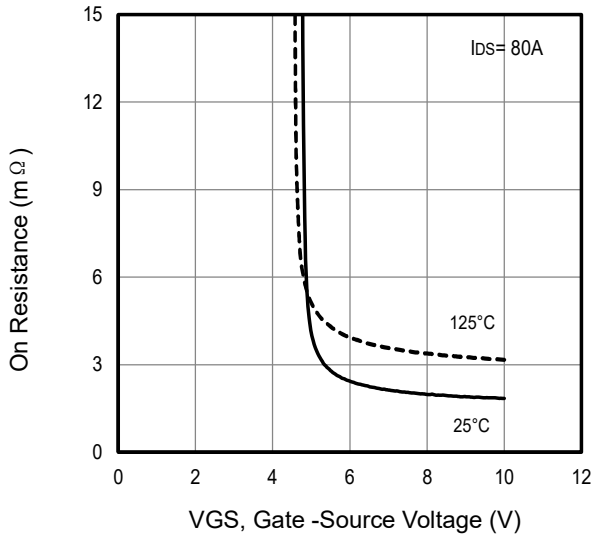


Fig5. Typical On Resistance Vs Gate -Source Voltage

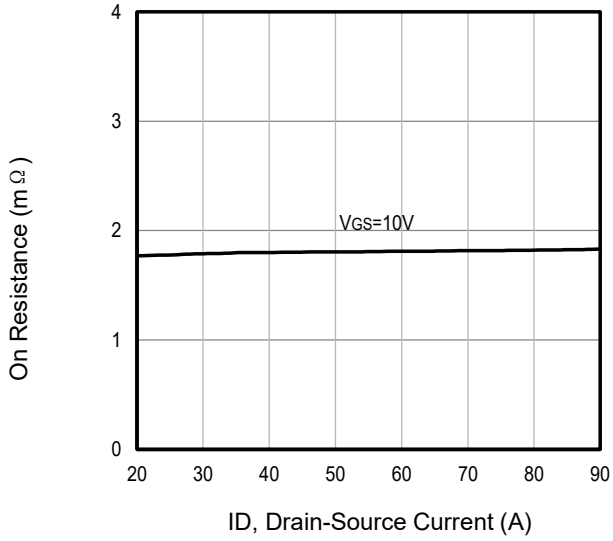


Fig6. Typical On Resistance Vs Drain Current

Typical Characteristics

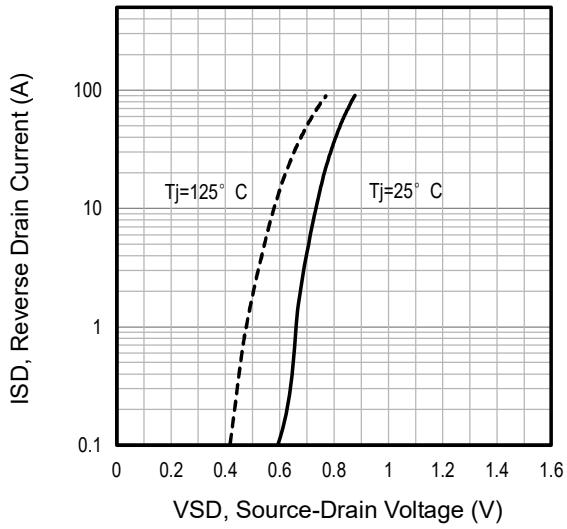


Fig7. Typical Source-Drain Diode Forward Voltage

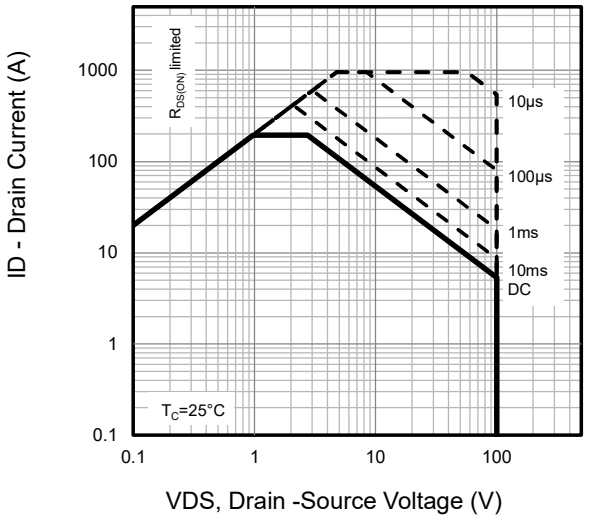


Fig8. Maximum Safe Operating Area

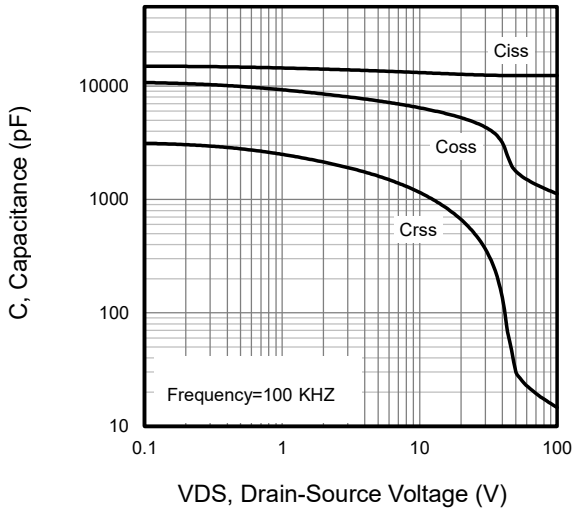


Fig9. Typical Capacitance Vs. Drain-Source Voltage

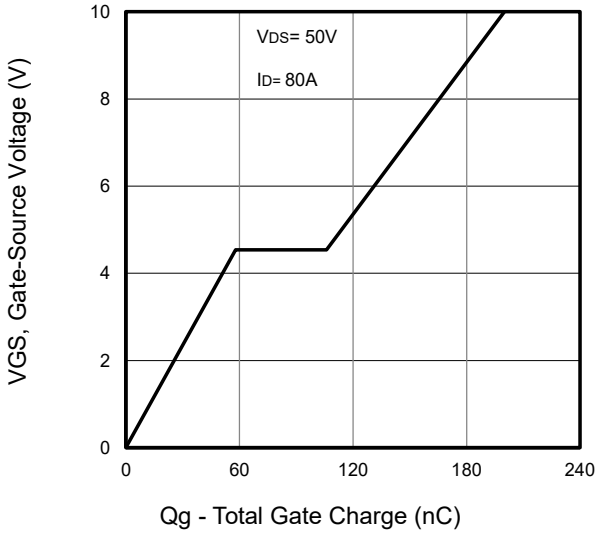


Fig10. Typical Gate Charge Vs. Gate-Source Voltage

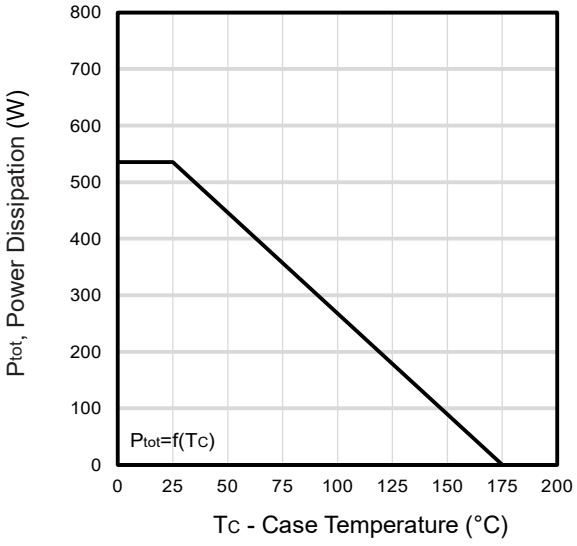


Fig11. Power Dissipation Vs. Case Temperature

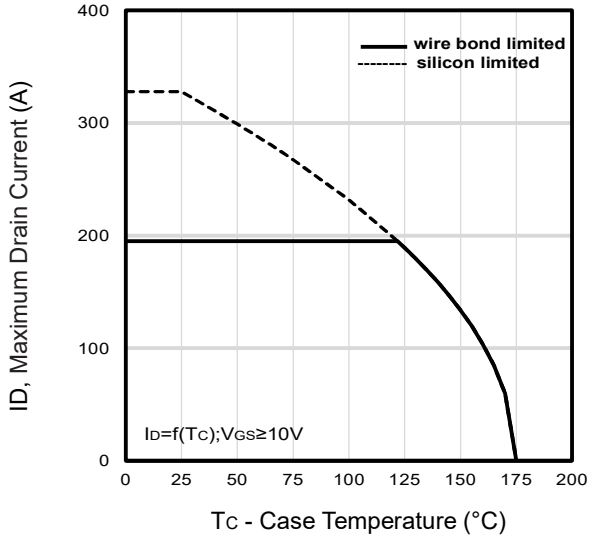


Fig12. Maximum Drain Current Vs. Case Temperature

Typical Characteristics

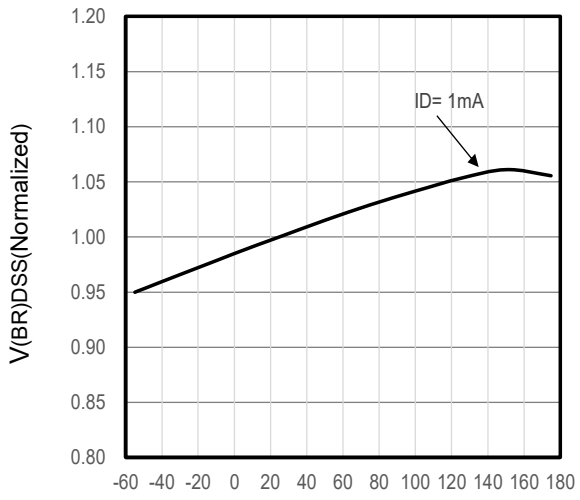


Fig13. Typical $V_{(BR)DSS}$ Vs Tj

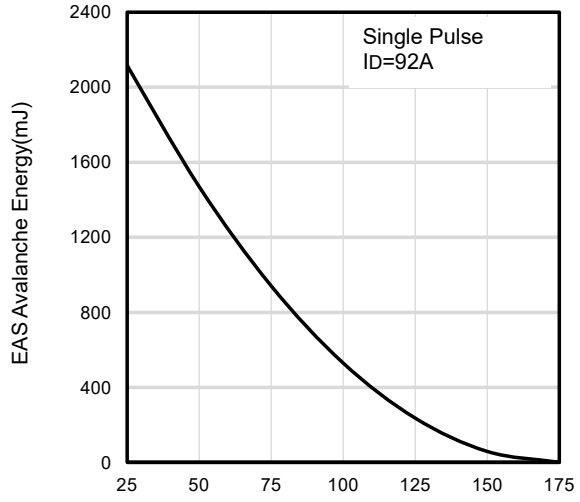


Fig14. Maximum Avalanche Energy vs Temperature (°C)

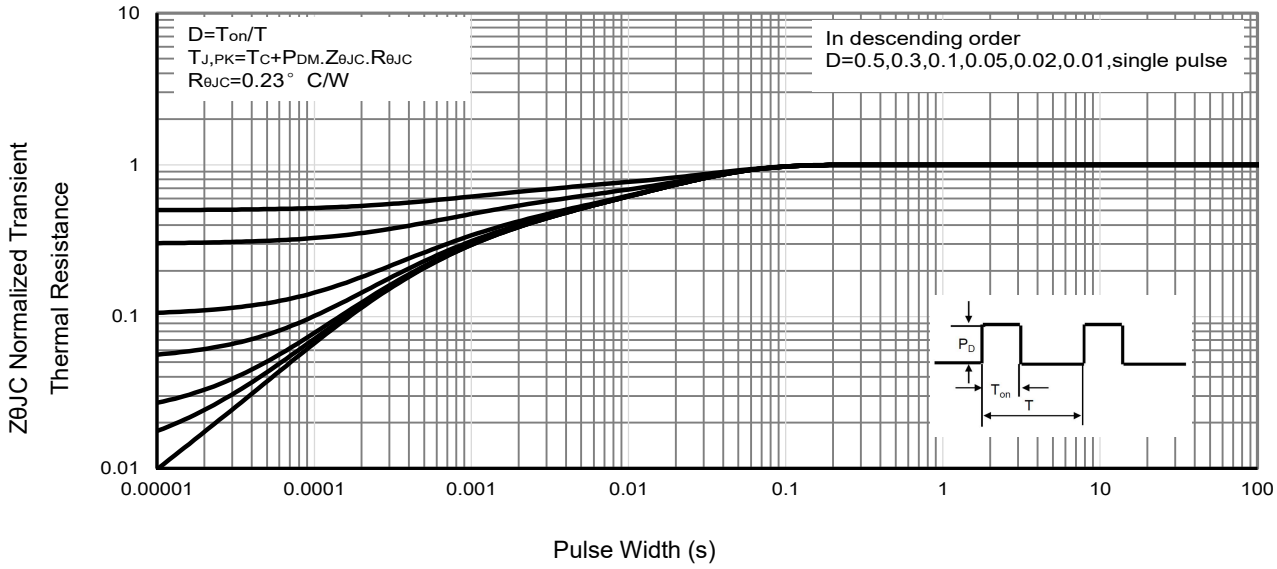


Fig15 . Normalized Maximum Transient Thermal Impedance

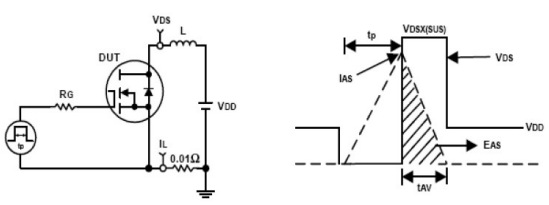


Fig16. Unclamped Inductive Test Circuit and waveforms

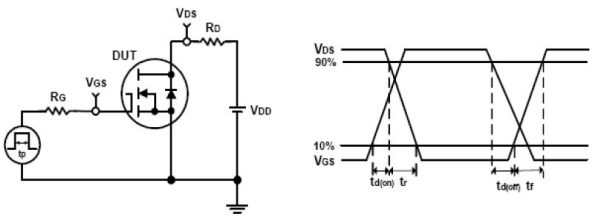
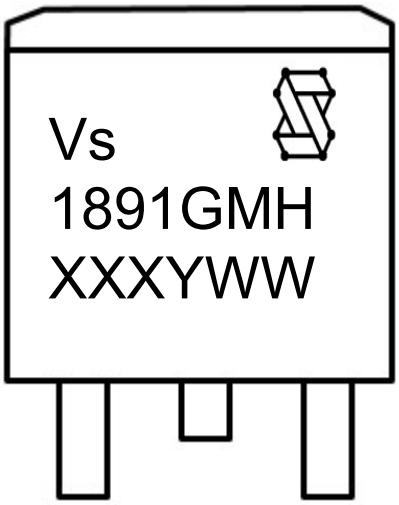


Fig17. Switching Time Test Circuit and waveforms

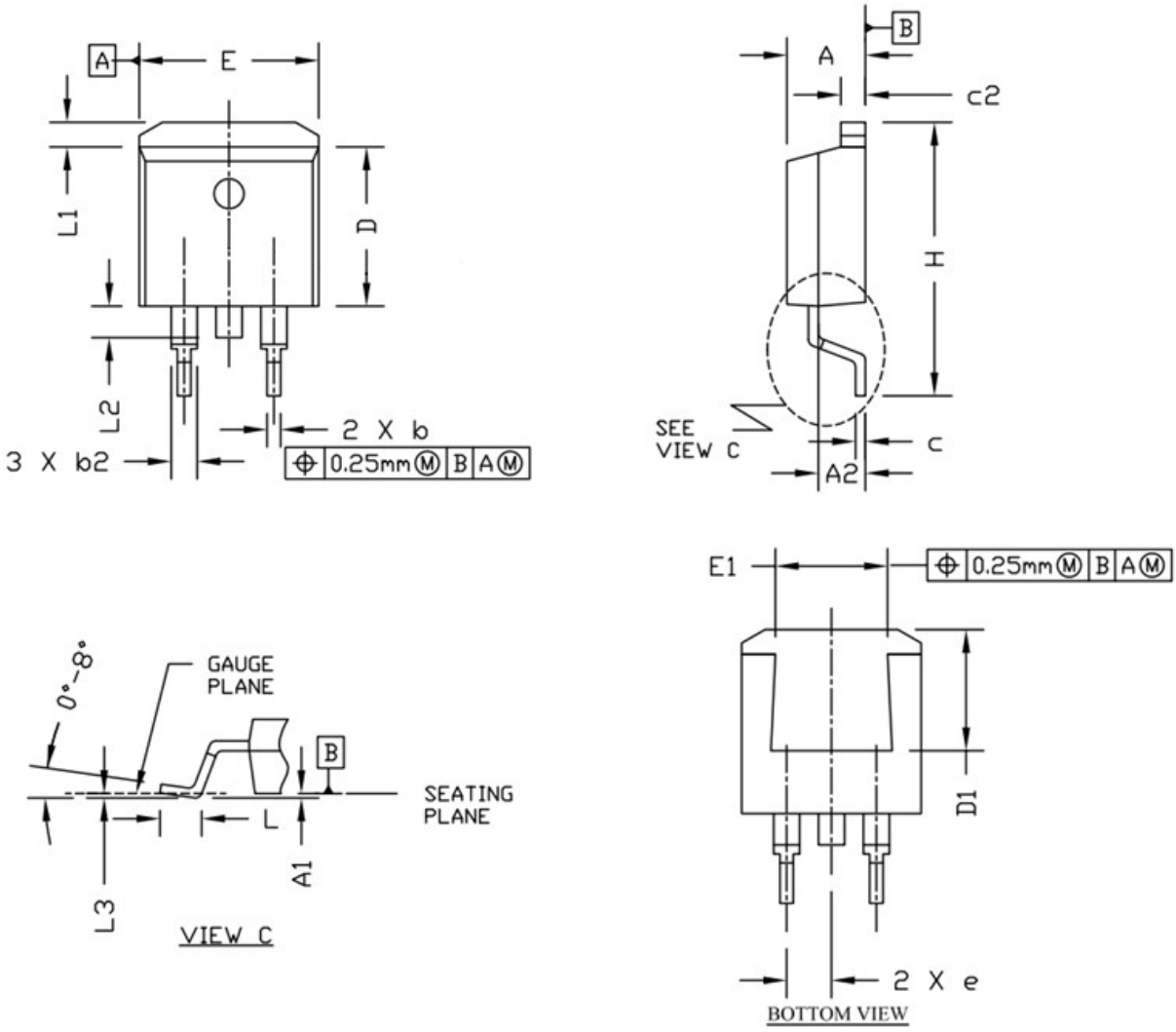
Marking Information



1st line: Vergiga Code（Vs）， Vergiga Logo
2nd line: Part Number（1891GMH）
3rd line: Date code （XXXYWW）
XXX: Wafer Lot Number Code , code changed with Lot Number
Y: Year Code ， refer to table below
WW: Week Code (01 to 53)

Code	C	D	E	F	G	H	J	K	L	M	N	P	Q	R	S	T
Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030

TO-263 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	4.400	4.570	4.700
A1	0.000	0.100	0.200
A2	2.300	2.400	2.500
b	0.700	0.800	0.900
b2	1.200	1.270	1.360
c	0.381	0.500	0.737
c2	1.220	1.300	1.350
D	8.600	9.200	9.300
D1	6.860		
e	2.540 BSC		
E	9.780	9.880	10.260
E1	6.225		
H	14.700	15.100	15.500
L	2.000	2.550	2.750
L1	1.000	1.200	1.400
L2	1.300	1.600	1.700
L3	0.255 BSC		

Notes:

1. Refer to JEDEC TO-263 variation AB
2. Dimension "D" & "E" do NOT include mold flash, mold flash shall not exceed 0.127mm per side.